AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) An apparatus comprising:

a plurality of pliant conductive elements, a first end of one of the plurality of pliant conductive elements to be electrically coupled to a first electrical contact of an integrated circuit substrate and a second end of the one of the plurality of pliant conductive elements to be electrically coupled to a second electrical contact of an integrated circuit die; and

a pliant material in which the plurality of pliant conductive elements are disposed, the pliant material comprising a pliant dielectric material.

2. (cancelled)

3. (cancelled)

4. (cancelled)

5. (currently amended) An apparatus according to ~~Claim 4,~~ Claim1, wherein the integrated circuit substrate comprises an integrated circuit package.

6. (currently amended) An apparatus according to ~~Claim 4,~~ Claim 1, wherein the integrated circuit substrate comprises a motherboard.

7. (cancelled)

8. (original) An apparatus according to Claim 1, wherein a first end of a second one of the plurality of pliant conductive elements is to be electrically coupled to a third electrical contact of the integrated circuit substrate and a second end of the second one of the plurality of pliant conductive elements is to be electrically coupled to a fourth electrical contact of the integrated circuit die.

9. (withdrawn) A method comprising:

forming an integral conductive element, the integral conductive element defining a plurality of recesses;

depositing a first pliant material in the plurality of recesses to form a first structure;

removing portions of the integral conductive element to form a plurality of pliant conductive elements; and

depositing a second pliant material around the plurality of pliant conductive elements to form a second structure.

10. (withdrawn) A method according to Claim 9, further comprising:

placing the first structure on a carrier after depositing the first pliant material; and

removing the second structure from the carrier after depositing the second pliant material.

11. (withdrawn) A method according to Claim 10, wherein placing the first structure on a carrier comprises:

placing the first structure on a release layer disposed on a carrier, and

wherein removing the second structure from the carrier comprises:

releasing the second structure from the release layer.

12. (withdrawn) A method according to Claim 10, further comprising:

bonding a first end of one of the plurality of pliant conductive elements to a first electrical contact of an integrated circuit substrate and a second end of the one of the plurality of pliant conductive elements to a second electrical contact of an integrated circuit die.

13. (withdrawn) A method according to Claim 10, wherein depositing the second pliant material comprises:

depositing a second pliant material around the plurality of pliant conductive elements to form the second structure having a first side and a second side,

wherein the first side includes the first pliant material, the second pliant material and a plurality of first ends of a respective plurality of pliant conductive elements, and

wherein the second side includes the second pliant material and a plurality of second ends of the respective plurality of pliant conductive elements.

14. (withdrawn) A method comprising:

depositing a plurality of elements on a carrier, the plurality of elements comprising first pliant material;

depositing an integral conductive element on the plurality of elements;

removing portions of the integral conductive element to form a plurality of pliant conductive elements; and

depositing a second pliant material around the plurality of pliant conductive elements to form a first structure.

15. (withdrawn) A method according to Claim 14, further comprising:

removing the first structure from the carrier after depositing the second pliant material.

16. (withdrawn) A method according to Claim 15, wherein depositing the plurality of elements on the carrier comprises:

depositing the plurality of elements on a release layer disposed on the carrier, and

wherein removing the first structure from the carrier comprises:

releasing the first structure from the release layer.

17. (withdrawn) A method according to Claim 14, further comprising:

bonding a first end of one of the plurality of pliant conductive elements to a first electrical contact of an integrated circuit substrate and a second end of the one of the plurality of pliant conductive elements to a second electrical contact of an integrated circuit die.

18. (withdrawn) A method according to Claim 14, wherein depositing the second pliant material comprises:

depositing a second pliant material around the plurality of pliant conductive elements to form the second structure having a first side and a second side,

wherein the first side includes the first pliant material, the second pliant material and a plurality of first ends of a respective plurality of pliant conductive elements, and

wherein the second side includes the second pliant material and a plurality of second ends of the respective plurality of pliant conductive elements.

19. (currently amended) A device comprising:

an integrated circuit die comprising a first plurality of electrical contacts;

an integrated circuit substrate comprising a second plurality of electrical contacts; and

an interconnect patch comprising a plurality of pliant conductive elements, a first end of one of the plurality of pliant conductive elements ~~coupled to~~ in physical contact with one of the first plurality of electrical contacts and a second end of the one of the plurality of pliant conductive elements ~~coupled to~~ in physical contact with one of the second plurality of electrical contacts.

20. (currently amended) A device according to Claim 19, wherein a first end of a second one of the plurality of pliant conductive elements is ~~coupled to~~ in physical contact with a second one of the first plurality of electrical contacts and a second end of the second one of the plurality of pliant conductive elements is ~~coupled to~~ in physical contact with the second one of the second plurality of electrical contacts.

21. (withdrawn) A system comprising:

a microprocessor comprising:

an integrated circuit die comprising a first plurality of electrical contacts;

an integrated circuit substrate comprising a second plurality of electrical contacts; and

an interconnect patch comprising a plurality of pliant conductive elements, a first end of one of the plurality of pliant conductive elements coupled to one of the first plurality of electrical contacts and a second end of the one of the plurality of pliant conductive elements coupled to one of the second plurality of electrical contacts; and

a double data rate memory electrically coupled to the microprocessor.

22. (withdrawn) A system according to Claim 21, wherein a first end of a second one of the plurality of pliant conductive elements is coupled to a second one of the first plurality of electrical contacts and a second end of the second one of the plurality of pliant conductive elements is coupled to the second one of the second plurality of electrical contacts.